MICROMIRROR CHIP, MICROMIRROR DEVICE, AND OPTICAL DEVICE

ABSTRACT

The present disclosure provides a micromirror chip, a micromirror device, and an optical device, and pertains to the field of micro-electro-mechanical system technologies. The micromirror chip includes a substrate, a micromirror array, electrodes, an optical window, and a fixed ring. The micromirror array is located on a first surface of the substrate, the electrodes are located on a second surface of the substrate, and the first surface and the second surface are opposite in a thickness direction of the substrate. The fixed ring is fastened onto the first surface of the substrate, the micromirror array is located in inner space of the fixed ring, and the optical window is fastened onto the fixed ring and covers the micromirror array. During packaging of the micromirror chip, because the micromirror array is first sealed in a sealed space formed by the substrate, the fixed ring, and the optical window, in a subsequent packaging process, no small particles fall into an environment in which the micromirror array is located, so that a qualification rate of the packaged micromirror device can be improved, thereby improving a yield rate of the packaged micromirror device.

FIG. 1